



IXYS LLC (A Littelfuse Company)
 1590 Buckeye Drive, Milpitas Ca 95035

March 16, 2018

Certificate of Compliance RoHS 2

Herewith we confirm that IXYS Devices and Chip Products are in compliance with the requirements detailed in the Directive 2011/65/EU (Jan. 3, 2013) and with the June 4, 2015, the European Delegated Directive (EU) 2015/863 to the list of substances in the table below with one exception. IXYS devices currently use a high temperature leaded solder for chip attach allowable under RoHS exemption 7A until 2019 per Directive 2016/774/EU as of 18 May 2016 amending Annex II to Directive 2000/53/EC. The prior wording for 8e (RoHS 7a) was retained and will be reviewed in 2019 by the EUC.

Substance	Maximum Limit (ppm)
Lead (Pb)	1000
Cadmium (Cd)	100
Mercury (Hg)	1000
Hexavalent Chromium (Cr6+)	1000
Poly Brominated Biphenyls (PBB)	1000
Poly Brominated Diphenyl ethers (PBDE)	1000
<i>Bis(2-ethylhexyl) phthalate (DEHP)</i> (CAS: 117-81-7)	1000
<i>Benzyl butyl phthalate (BBP)</i> (CAS: 85-68-7)	1000
<i>Dibutyl phthalate (DBP)</i> (CAS: 84-74-2)	1000
<i>Diisobutyl phthalate (DIBP)</i> (CAS: 84-69-5)	1000

7(a)	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)
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